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Substitute Form PTO-1449 (Modified)

S. Department of Commerce

Attorney's Docket No. Application No. 05542-552001

Applicant

10/732,966

Information Disclosure Statement by Applicant (Use several sheets if necessary)

Chen et al. Filing Date

December 10, 2003

Group Art Unit 1763

(37 CFR §1.98(b))

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